Nihon Handa Co.,Ltd. Head Office : 16F ARCA CENTRAL 2-1 Kinshi 1-Chome, Sumida-ku, Tokyo 130-0013, JAPAN Tel.+81-3-3624-5771 Fax.+81-3-3624-5775

Solder paste for power device die bonding

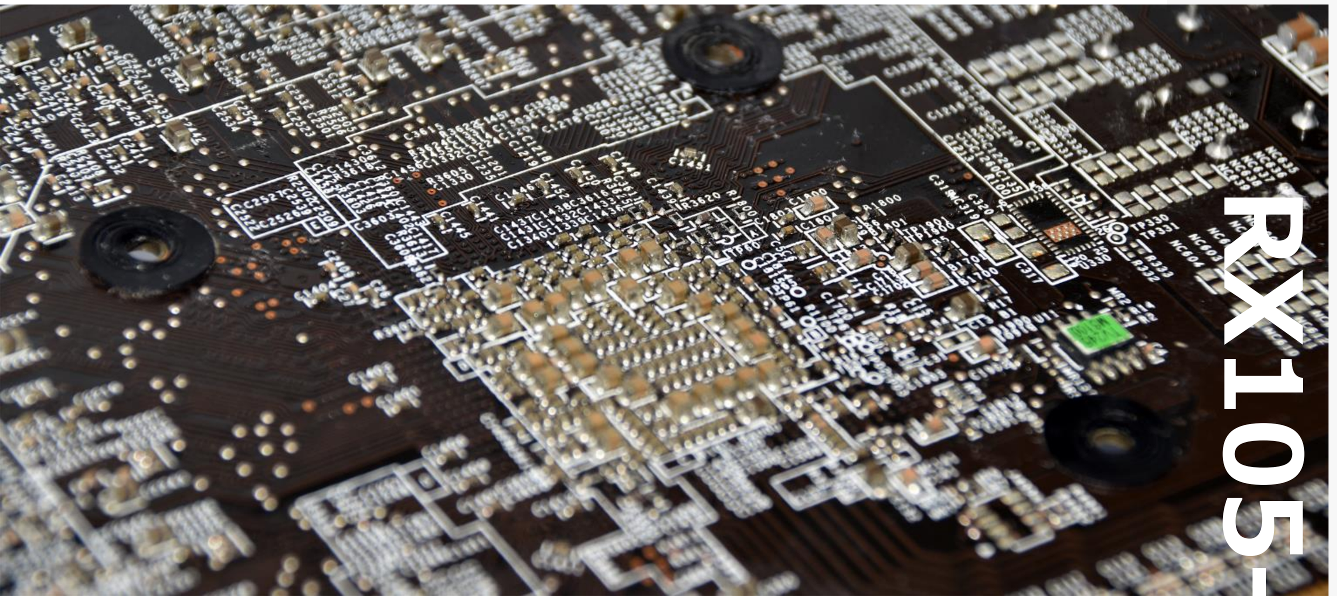
RX105-207SDO(HF-T)

Low residue · No clean · Low void · No halogen

- Reduced flux residue despite maintaining good wettability
- Environment-friendly non-halogen type
- Good void suppression effect comparable to halogen-added products

Die bond Solder Paste for Power Device

RX105-207SDO(HF-T)



Characteristics

Properties		Representative characteristics	Test method
Alloy composition		5Sn-Pb	JIS Z 3282
Solidus-Liquidus Temp.		300deg.C - 314deg.C	JIS Z 3198
Particle size		10 to 30μm	–
Standard flux content		10wt%	JIS Z 3197
Halide content		0.00%	JIS Z 3197
Flux type		ROL0	IPC J-STD-004
Copper plate corrosion test		Pass	JIS Z 3197
Silver chromate paper test		Pass	JIS Z 3197
Copper mirror test		Pass	JIS Z 3197
Electric insulation resistance test, SIR	40℃ 90%RH	1.0×10^{11} Ω	JIS Z 3197
	85℃ 85%RH	5.0×10^{8} Ω	JIS Z 3197
Fluidity	Viscosity	30 Pa・s	JIS Z 3284
	Thixotropic index	0.50	JIS Z 3284

The above values are not guaranteed figures but representative ones.

2020.01.001

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Die bond Solder Paste for Power Device

RX105-207SDO(HF-T)

Optimized flux design attainable both low residue and wettability

RX105-207SDO(HF-T)

Conventional halogen added product

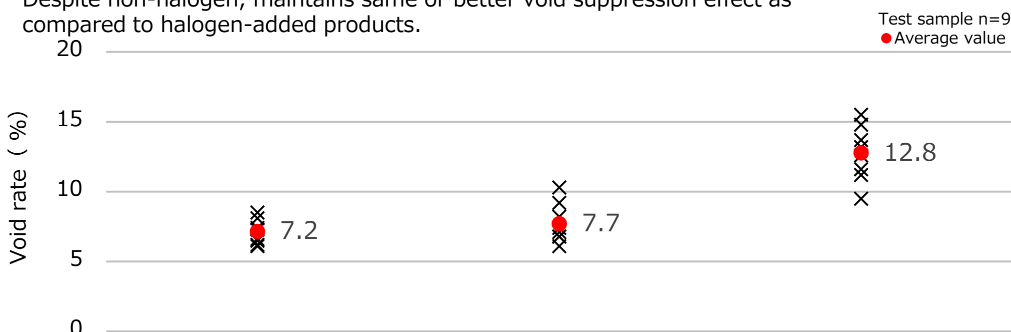
Conventional non-halogen product

Less flux residue than conventional products, better wettability than conventional non-halogen products.

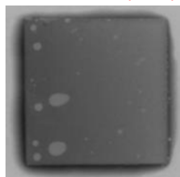
【Test condition】
N_2 Reflowing（O_2 concentration : 1000ppm）
Preheating : 180 to 190℃, 90 sec.　300℃ or more : 65 sec.
Peak temp. 340℃

Good void properties despite non-halogen

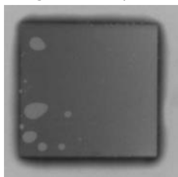
Despite non-halogen, maintains same or better void suppression effect as compared to halogen-added products.



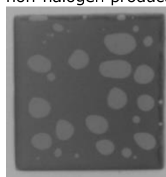
RX105-207SDO(HF-T)



Halogen added product



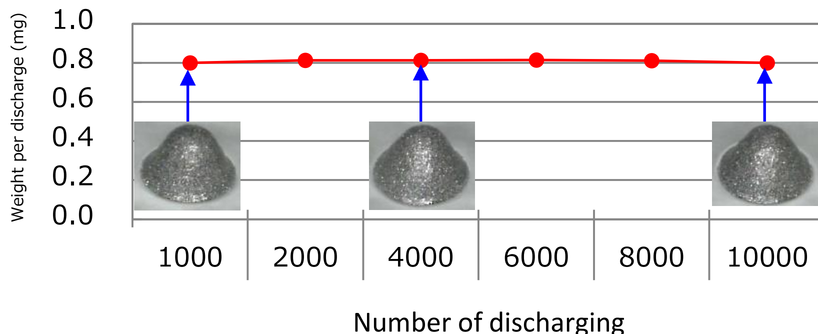
Conventional non-halogen product



【Test condition】
N2 Reflowing（O2 concentration : 1000ppm）
Preheating : 180 to 190℃, 90 sec.　300℃ or more : 65 sec. Peak temp. 340℃
Test parts : 5mm□Cu chip

Good discharging performance despite low flux content

Adjustable to the optimum viscosity for dispensing paste and achieved excellent shape of solder fillet and continuous discharging stability.



【Test condition】 Discharging pressure : 100kPa,
Discharging time : 0.5sec., Needle inner diameter : 0.34mm
Flux content: 10wt%

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